



Your KEY PARTNER for All Semiconductor Applications

Semiconductors Industrialisation Production Services











SYNERGIE CND GRO



contact : sales-psc@synergie-cad.fr





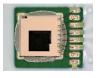
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Competences

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ELECTRONICS

- PCB design
- PCB fabrication
- PCB assembly
- Application boards
- Test boards
- Probe cards
- Reliability boards
- Cabling
- Chip On Board



SEMICONDUCTORS

- Wafers sourcing
- Packaging





- Wafer Test
- Final Test



- **Reliability Qualification**
- Supply Chain
- Storage

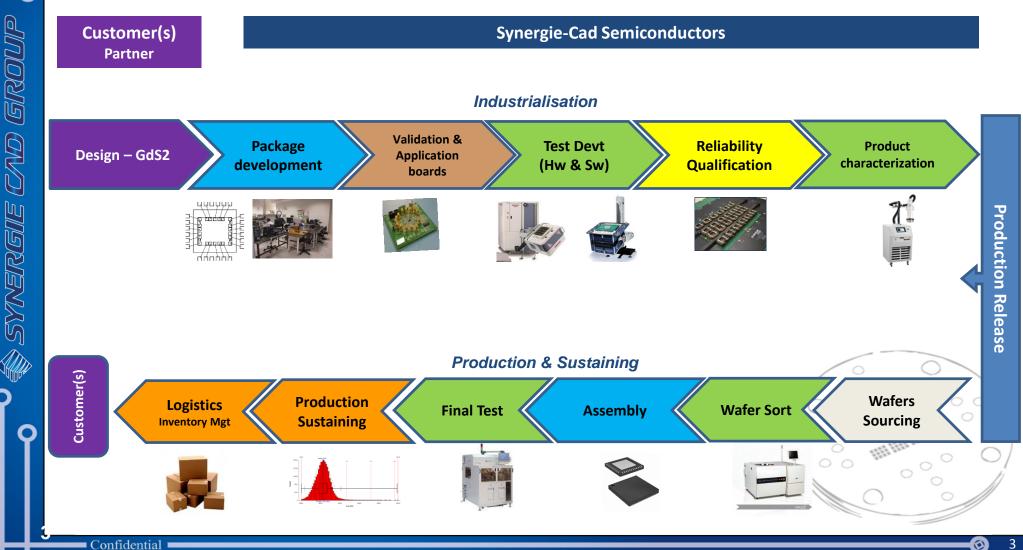


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Semiconductors Turn-Key Solutions

From 'Gds2 or wafers' to 'Finished Goods delivery'

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Test & Product Engineering

Test Solution Development

- Hardware (parametric cards, probe cards, loadboards)
- Software
- Specialties : Digital, Mixed-Signal, Analog, RF / MMW (up to 86GHz)
- Consumer / Industrial, Automotive

Product characterization

Prototyping & Production

- Europe
- Asia

GRO

SYNERGIE

- 6, 8, 12in. Probers [-55C / +200C]
- Automatic Handler

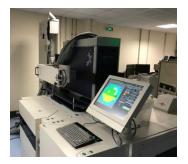
Production Sustaining

- Cost optimization
- Product Q.A. & PPAP

ATE's

- In-House : Xcerra Diamond-X, Credence Sapphire, Advantest V93K, Teradyne J750, Teradyne UltraFlex-RF
- Other competences : Teradyne Flex, Eagle ETS364, Diamond D10, Advantest T2000
- **Class 10K local environment**







Packaging - Assembly

From Prototyping to Large series

<u>Small & mid series in Europe internal Packaging line</u>

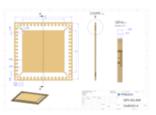
- Internal line / France Toulouse (previous Freescale line)
 - Moulded Frame packages (QFN, SO, QFP, DIL...)
 - Air cavity packages (QFN, SOIC, QFP...)
 - Ceramics packages (C-PGA, C-DIP, C-SOP, C-QFP...)
 - BGA / LGA packages (custom laminates, generic laminate available)
- Package Design
- Inspection : Xrays, Acoustic Microscopy

Partnership with major OSAT for mid and large series

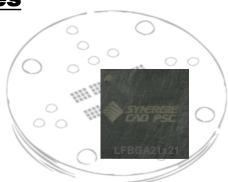
- Lead packages : QFP, SO, ...
- CSP Packages : QFN, WLCSP (Fan In)
- Organic packages : BGA, LGA, TE-FCBGA
- Optical packages : OLGA type















INTERNAL Production line Roadmap

Small & mid series

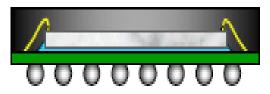
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LfBGA < 1.7mm pitch 1.7 / 1.0 / 0.8mm



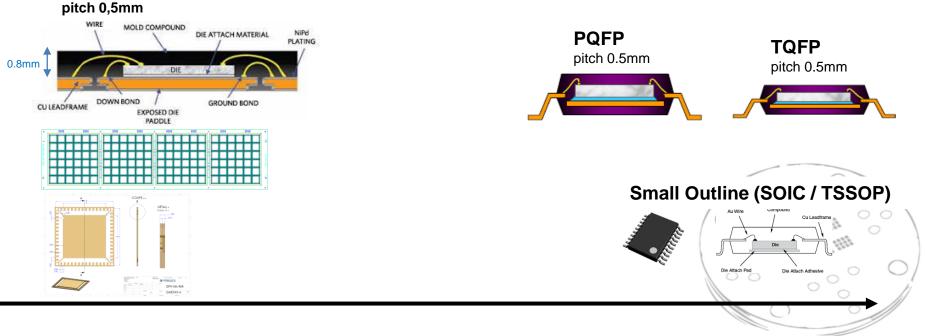
PBGA < 2.4mm pitch 1.0 mm



FCBGA pitch 1,0mm



T-QFN < 1.1mm (3x3 to 12x12 dual row 156L)



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Reliability

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Jedec, AEC-Q100,...

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CND GROUP

SYNERGIE

Qualification, Burn'In, L.A.T, Monitoring

Environmental tests

- HTOL / LTOL
- ТНВ 85С/85% RH
- Hast
- Preconditionning/Reflow
- Thermal Cycling / VRT 15C/min.
- THNB/Thu 85C/85%
- High Temperature Storage 300c
- (ESD / Latch-Up)
 - ESD HBM / MM
 - ESD CDM
 - Latch-Up
- Xrays inspection External Visual Decapsulation
- Delamination analysis Acoustic Microscopy (SAM)



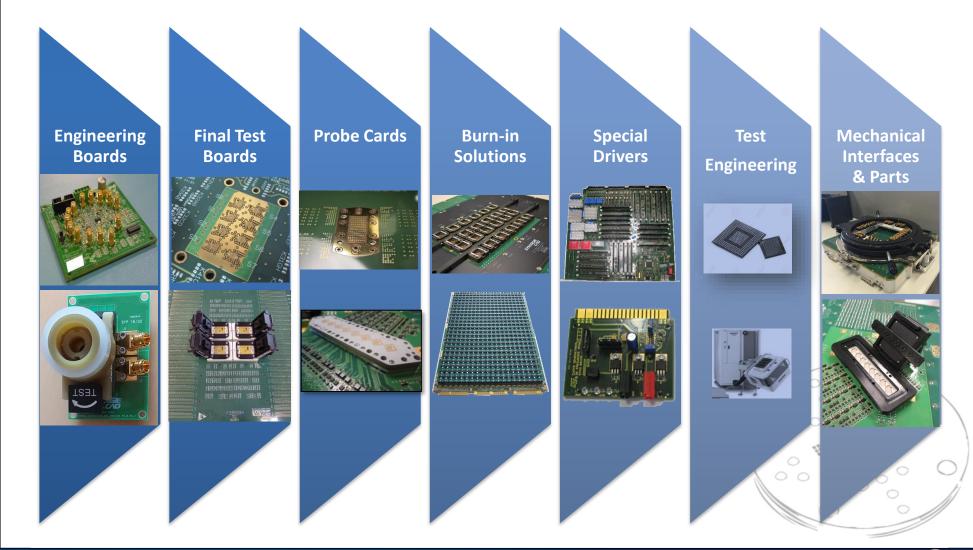




Wide Hardware Capabilities for Semiconductors

In-House development and fabrication

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Confidential

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SYNERGIE CAD GROUP

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Why choosing Synergie Cad Semiconductors...

- Staff with more than 15years average experience in Semiconductors development, industrialisation and manufacturing
- True TurnKey offer (Packaging, Test, Reliability, Supply chain, PCB)
- Large experience and deep knowHow in New Product Introduction, product industrialisation, and production sustaining / Quality Assurance from small to High volumes.... We are not only a simple Test House or Assy house ...
- Unique combined offer in both Packaging & Test services
 - Packaging Line for prototyping & small series in Toulouse (France)
 - Partnership with Tier1 OSAT for mid & large series
- Flexible, reactive, and 'easy-to-work with' organization

